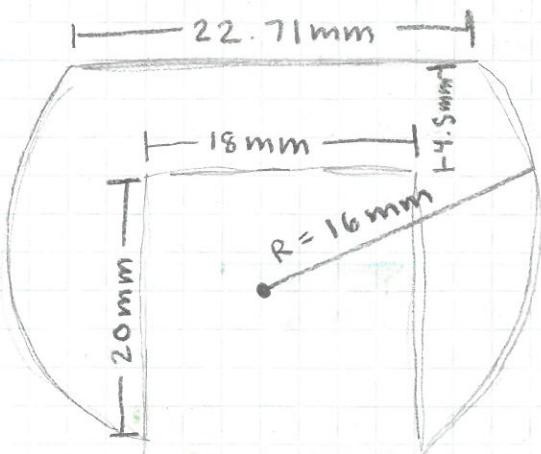
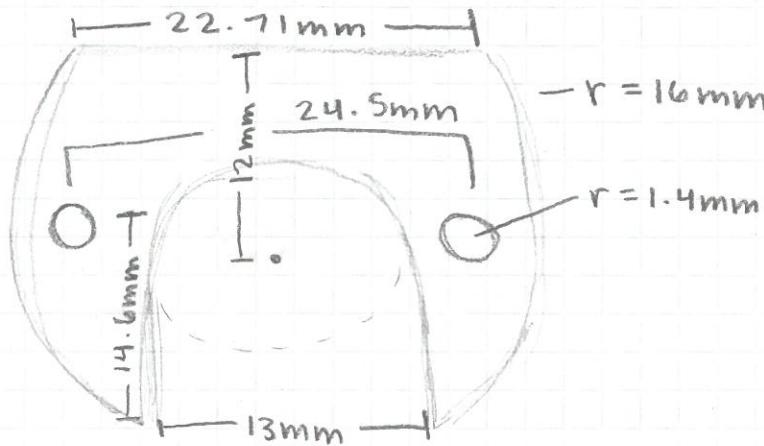


Sketch #1



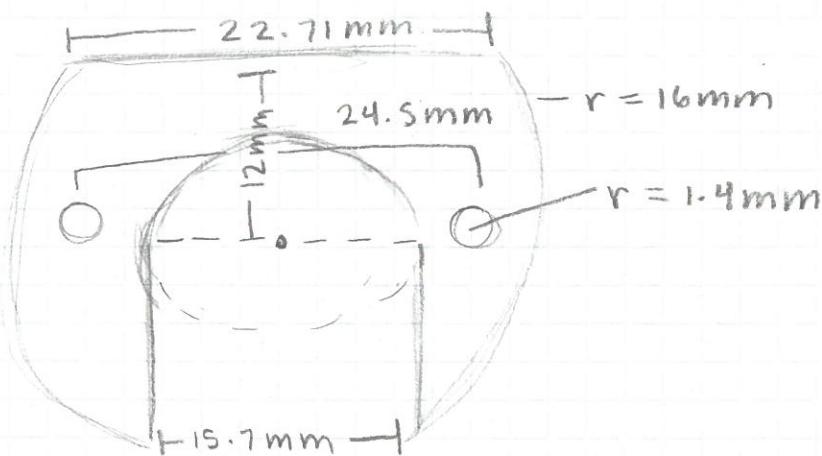
height = 40mm
position z = 0mm

Sketch #2a



r = 16mm height = 1.7mm
position z = -1.7mm

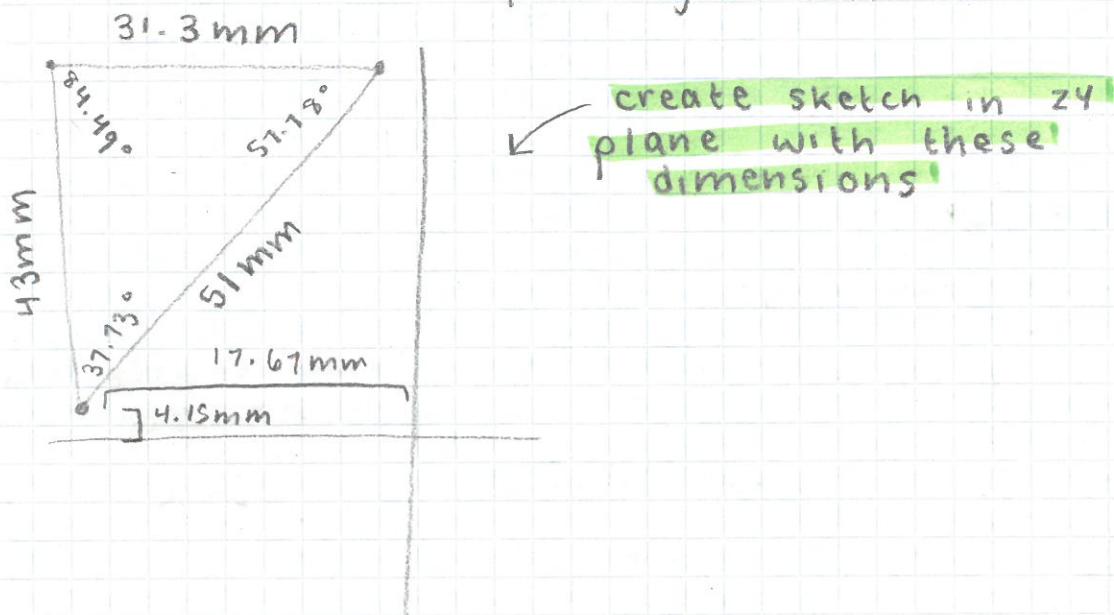
Sketch #3



height = 1.7mm
position z = -3.5mm

★ repeat sketch 2a (name this 2b.)
 where height = 1.7mm and position z = -5.2mm
 and repeat sketch 2a again (name this
 2c) where height = 4.8mm and
 position z = -10mm.

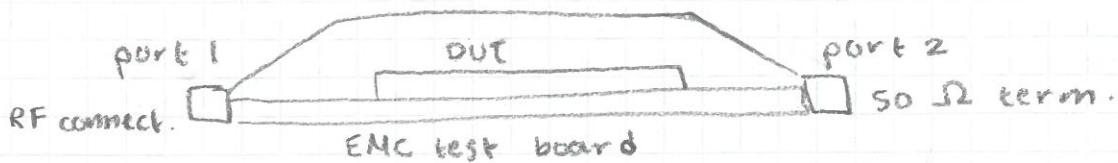
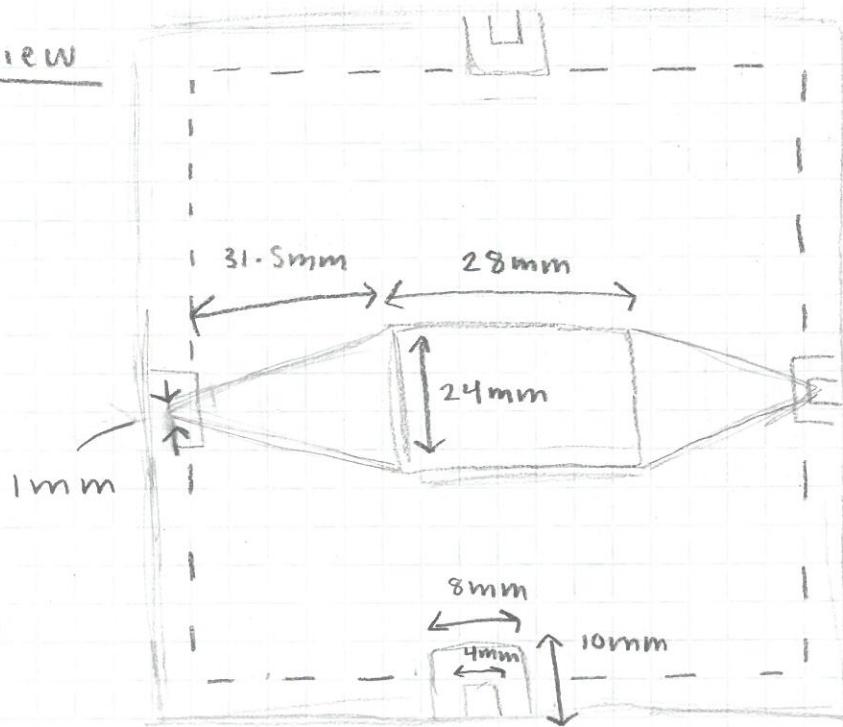
After sketching and padding is complete,
 create a new sketch in the body
 'Sketch #1'. Make this sketch a 'pocket' to create
 the angled surface



Finally, round all outward, forward facing edges by 1mm.

side view

IC - stripline

top viewLayers of test board

Layer	Descript.	Material	Thickness
1	Signal	copper prepreg	0.071 mm 0.152 mm
2	gnd	copper prepreg	0.035 mm 1.028 mm
3	VCC	copper prepreg	0.035mm 0.152 mm
4	Signal	copper	0.071mm

specifications

frequency range - 150 kHz to 3 GHz
VSWR - < 1.25

stripline height - the height of the dut must be less than 50% of the conductors height
stripline width - the width of the device under test must be less than 110% of the conductor width